

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hiroko Yamada</td> <td>01/25/2013</td> </tr> <tr> <td>Takahide Mizawa</td> <td>01/25/2013</td> </tr> </tbody> </table>		Name	Execution Date	Hiroko Yamada	01/25/2013	Takahide Mizawa	01/25/2013				
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Soken Chemical & Engineering Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>29-5, Takada 3-chome, Toshima-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>1718531</td> </tr> </table>		Name:	Soken Chemical & Engineering Co., Ltd.	Street Address:	29-5, Takada 3-chome, Toshima-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	1718531
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 4129455933 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 412-471-8815</p> <p>Email: assignments@webblaw.com</p> <p>Correspondent Name: THE WEBB LAW FIRM, P.C.</p> <p>Address Line 1: ONE GATEWAY CENTER</p> <p>Address Line 2: 420 FT. DUQUESNE BLVD, SUITE 1200</p> <p>Address Line 4: PITTSBURGH, PENNSYLVANIA 15222</p>											
ATTORNEY DOCKET NUMBER:	1217-130239										
NAME OF SUBMITTER:	Kent E. Baldauf										
<p>Total Attachments: 3</p> <p>source=RECOVER#page1.tif</p> <p>source=ASSIGN#page1.tif</p> <p>source=ASSIGN#page2.tif</p>											

OP \$40.00 13814325

**RECORDATION FORM COVER SHEET
PATENTS ONLY**

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Hiroko YAMADA
Takahide MIZAWA

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) January 25, 2013

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)

Name: Soken Chemical & Engineering Co., Ltd.

Internal Address: _____

Street Address: 29-5, Takada 3-chome

Toshima-ku, Tokyo

City: _____

State: _____

Country: JAPAN Zip: 1718531

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

13/814,325

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Kent E. Baldauf

Internal Address: The Webb Law Firm

Street Address: One Gateway Center
420 Ft. Duquesne Blvd., Ste 1200

City: Pittsburgh

State: PA Zip: 15222

Phone Number: 412-471-8815

Fax Number: 412-945-5933

Email Address: assignments@webblaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☒ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers 4775
Expiration Date 05/2015

b. Deposit Account Number 23-0650

Authorized User Name _____

9. Signature:

Kent E. Baldauf
Signature

February 5, 2013
Date

Kent E. Baldauf, Registration No. 25,826

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

3

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

Assignment of Application

INSERT NAMES
AND RESIDENCE
ADDRESS OF
THE INVENTORS:

WHEREAS, I (WE) 1) Hiroko YAMADA and 2) Takahide MIZAWA of c/o SOKEN
CHEMICAL & ENGINEERING CO., LTD., 13-1, Hirosehighashi 1-chome,
Sayama-shi, Saitama 3501320 Japan, respectively,

INSERT TITLE OF
INVENTION:

have invented certain new and useful improvements in: "RESIN MOLD FOR NANOIMPRINTING
AND PRODUCTION METHOD THEREOF"

(Application No. 13/814,325 , filed August 3, 2011), and

INSERT NAMES
AND ADDRESS OF
COMPANY OR
OTHER ASSIGNEE:

WHEREAS, SOKEN CHEMICAL & ENGINEERING CO., LTD.

(hereinafter referred to as "ASSIGNEE") having a place of business at : 29-5, Takada
3-chome, Toshima-ku, Tokyo 1718531 Japan is desirous of acquiring the entire right,
title and interest in and to said invention and in and to any Letters Patent that may be granted
therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is
hereby acknowledged, and for other good and valuable consideration, I(WE), by these presents do
sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in
the United States and its territorial possessions and in all foreign countries and the entire right,
title and interest in and to any and all Letters Patent which may be granted therefor in the United
States and its territorial possessions and in any and all foreign countries and in and to any and all
divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and its
territorial possessions and any and all foreign countries to issue any and all of said Letters Patent,
when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and
to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the
full end of the term for which said Letters Patent may be granted, as fully and entirely as the same
would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letter Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNMEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of THE WEBB LAW FIRM of One Gateway Center
420 Fort Duquesne Blvd.,
Suite 1200, Pittsburgh PA 15222

United States the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: January 25, 2013

Hiroko Yamada .

(Signature of Inventor) Hiroko YAMADA

Date: January 25, 2013

T. Mizawa

(Signature of Inventor) Takahide MIZAWA

Date: _____

(Signature of Inventor)

Date: _____

(Signature of Inventor)

Date: _____

(Signature of Inventor)

Date: _____

(Signature of Inventor)

Date: _____

(Signature of Inventor)

Date: _____

(Signature of Inventor)

Date: _____

(Signature of Inventor)

Date: _____

(Signature of Inventor)